

400GbE PCS Architectural Requirements

IEEE 400 Gb/s Ethernet Study Group

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Introduction

- The following slides explore the architectural requirements for a 400GbE PCS

High Level Architectural Requirements

- Define an optional AUI
 - Chip-to-Module and Chip-to-Chip
- Support EEE
- Appropriate support for OTN
- Support FEC(s) either initially or in the future depending on the PMD or AUI requirements
 - Location of the FEC is TBD
- Ability to support (and change as necessary) TBD lane widths
 - Options detailed later in this document
- Define a common service interface for all sublayers
- Define an optional CDGMII
- Provide appropriate support for multi-rate implementations
 - For example common lane rates, common PCS technology etc.

AUI and MDI Evolution

- A big part of what the PCS architecture should support is a graceful evolution of the AUI and the MDI
- The next 8 slides look at the possible evolution of the AUIs and MDIs
- A possible evolution of the AUI is
 - CDAUI-16 -> CDAUI-8 -> CDAUI-4
 - CDAUI-16 -> CDAUI-10 -> CDAUI-4

It is also possible to define CDAUI-10 and CDAUI-8 at the same time
- The MDI likely won't evolve in a straight line due to the varying reach and medium needs, the PCS needs to be flexible enough to support the various lane requirements over time (a lane can be a lambda, fiber, copper cable or combination)

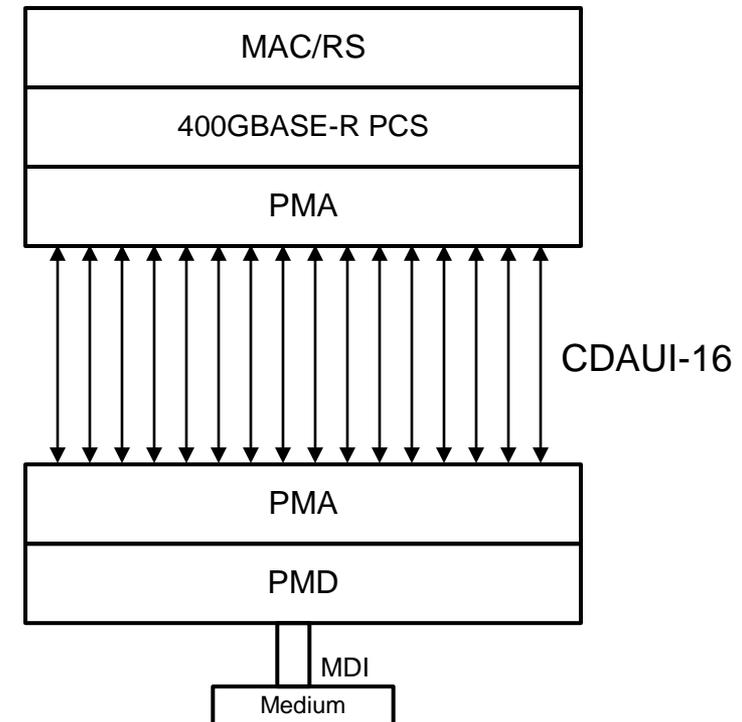
Electrical Interface Option #1

➤ Properties:

- 16 lanes
- 25.78125 Gb/s per lane
- NRZ signaling
- 10dB loss for chip-to-module
- 15-20dB loss for chip-to-chip
- No FEC required to close the interfaces*

➤ Benefits

- Leverages existing CAUI-4 work

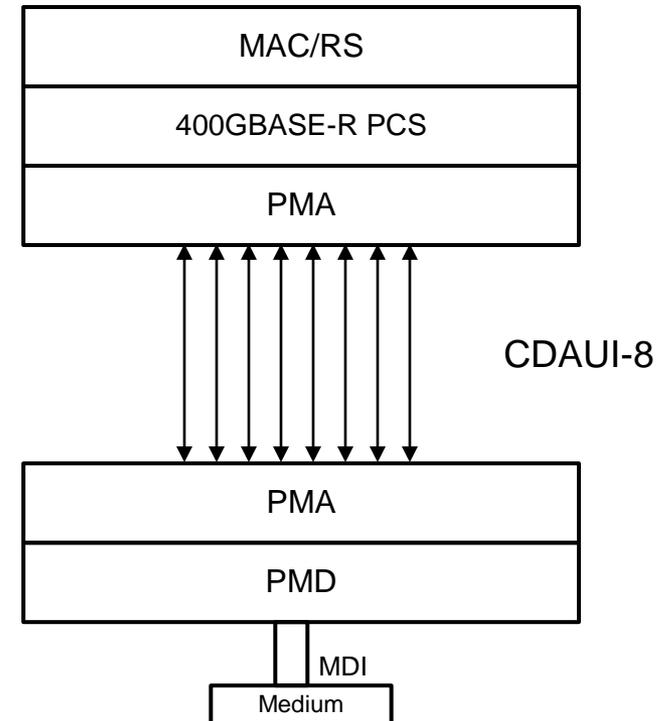


* If FEC is always sent, this interface can take advantage of that with a relaxed BER budget

Electrical Interface Option #2

➤ Properties:

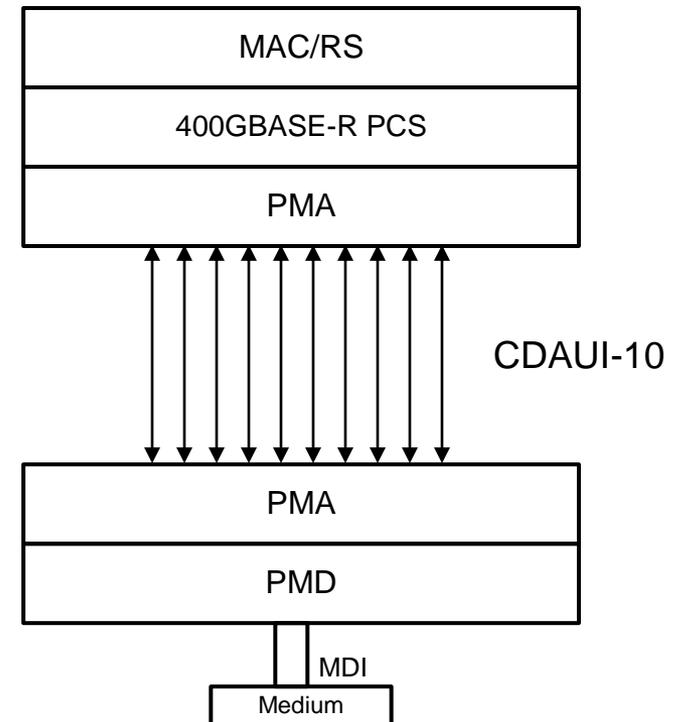
- 8 lanes
- 51.5625 Gb/s per lane
- NRZ or PAMn signaling, TBD
- Loss is TBD for chip-to-module and chip-to-chip interfaces
- Need for FEC is TBD



Electrical Interface Option #3

► Properties:

- 10 lanes
- 41.25 Gb/s per lane
- NRZ? signaling
- 20dB? loss for chip-to-module
- Loss is TBD for chip-to-module and chip-to-chip interfaces
- Need for FEC is TBD
- Use case for supporting 40G VCSELs?
 - Question to answer: Is there is likely to be something that works for 40GBASE-?R10 but not 40GBASE-?R8 that is not a short term technology limit

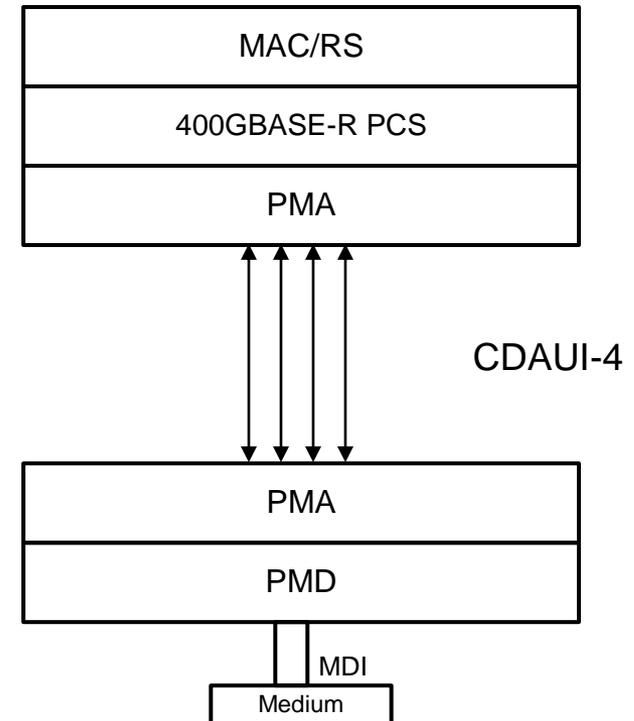


Can MLG be used for this application instead of defining a CDAUI-10?

Electrical Interface Option #4

► Properties:

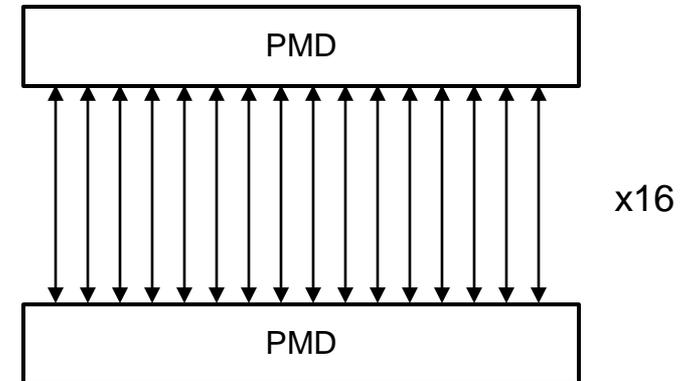
- 4 lanes
- 103.125 Gb/s per lane
- PAMn? signaling
- dB? loss for chip-to-module
- ?dB loss for chip-to-chip
- Likely need strong FEC to close the interfaces?



Possible Re-use Optical/Electrical PMD

► Properties:

- 16 lanes
- 25.78125 Gb/s per lane
- NRZ signaling
- FEC required for some possible variations (SR16, CR16 for instance), not needed for others (4xLR4)

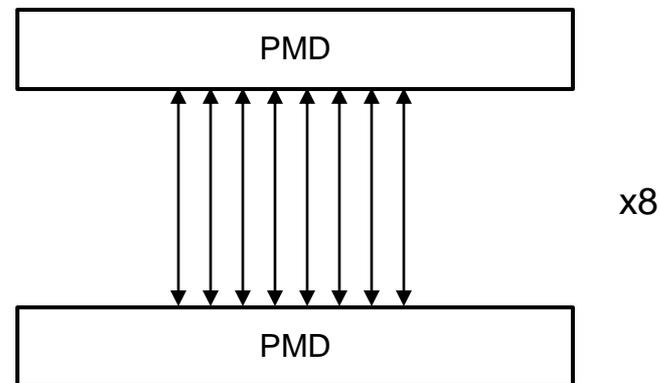


Note: number of lanes can be constituted from lambdas, fibers, twinax or some combination

Possible Future Optical/Electrical PMD

► Properties:

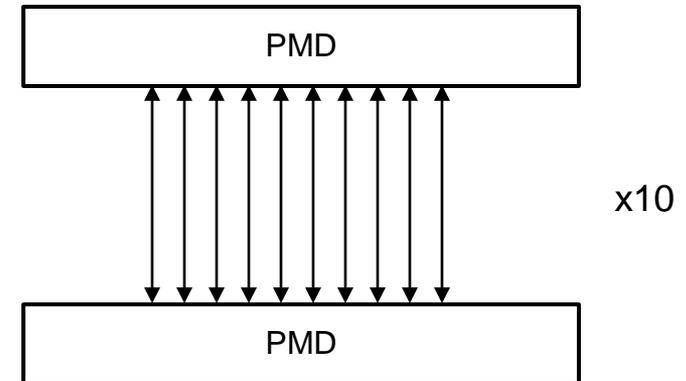
- 8 lanes
- 51.5625 Gb/s per lane
- NRZ or PAM_n signaling depending on reach and medium?
- FEC required?



Possible Future Optical/Electrical PMD?

► Properties:

- 10 lanes
- 41.25 Gb/s per lane
- NRZ or PAMn signaling?
- FEC required??
- Re-use of 40GbE technology?
- Use case for supporting 40G VCSELs?
 - Question to answer: Is there is likely to be something that works for 400GBASE-?R10 but not 400GBASE-?R8 that is not a short term technology limit

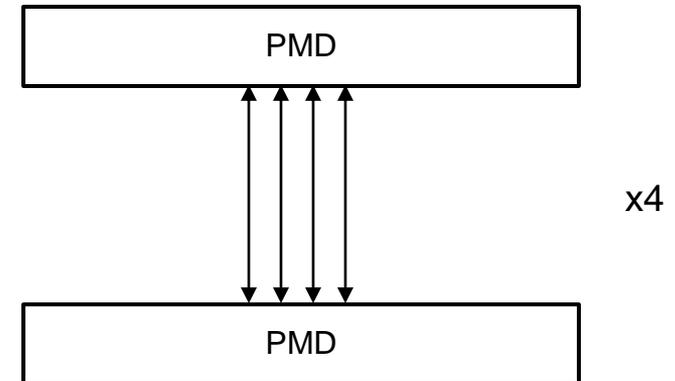


Can MLG be used for this application instead of defining a CDAUI-10?

Possible Future Optical/Electrical PMD

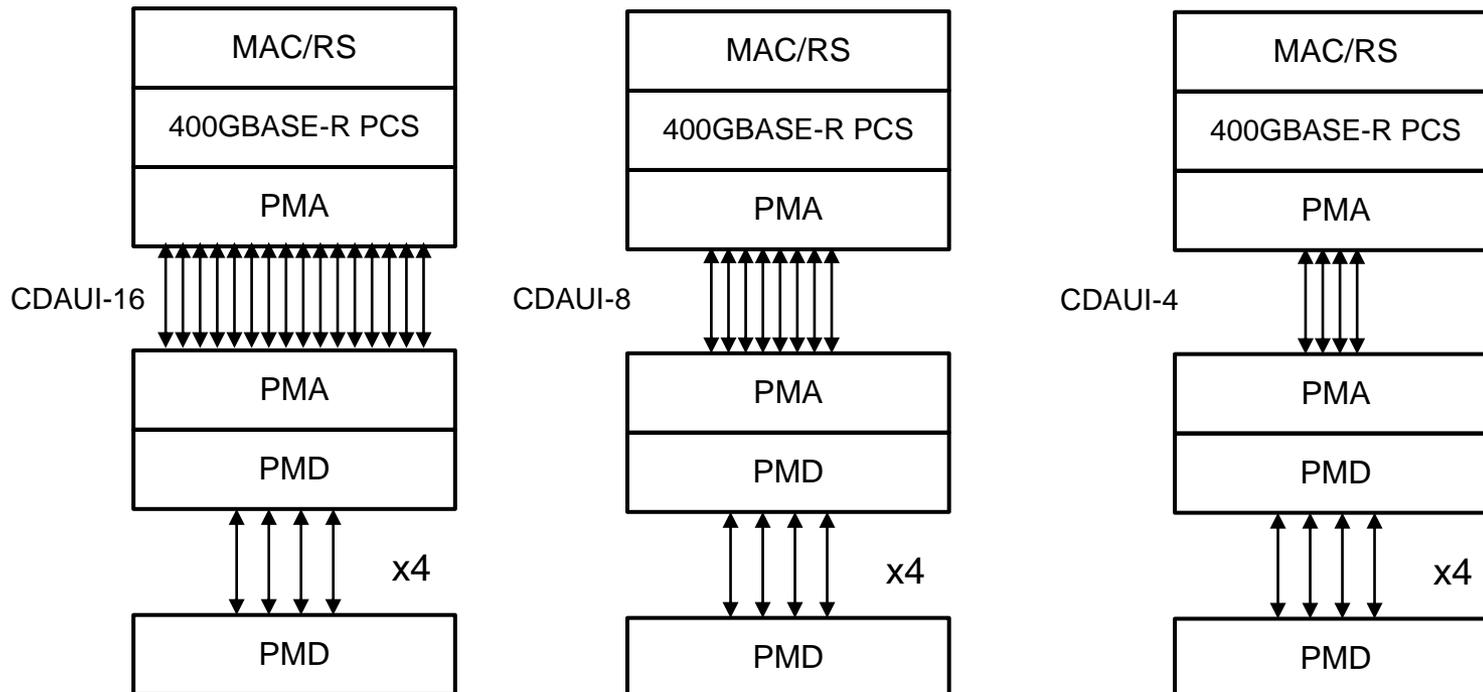
► Properties:

- 4 lanes
- 103.125 Gb/s per lane
- PAMn, DMT etc..
- FEC required
- Assuming that with higher order modulation alignment or other needed information can be added to the structure, does the PCS support for 4 lanes matter?
- This is when a backplane PMD might make sense?



Long Lived Optical Interface

- Below shows an example of a possible long lived PMD with 3 electrical generations
- We should strive to define an architecture that is long lived and does not unduly burden the optics module
- The need or not for FEC on the electrical interface can complicate the module if that FEC must be terminated in the module
 - Even worse is if different FECs are used, Latency is multiplied for instance

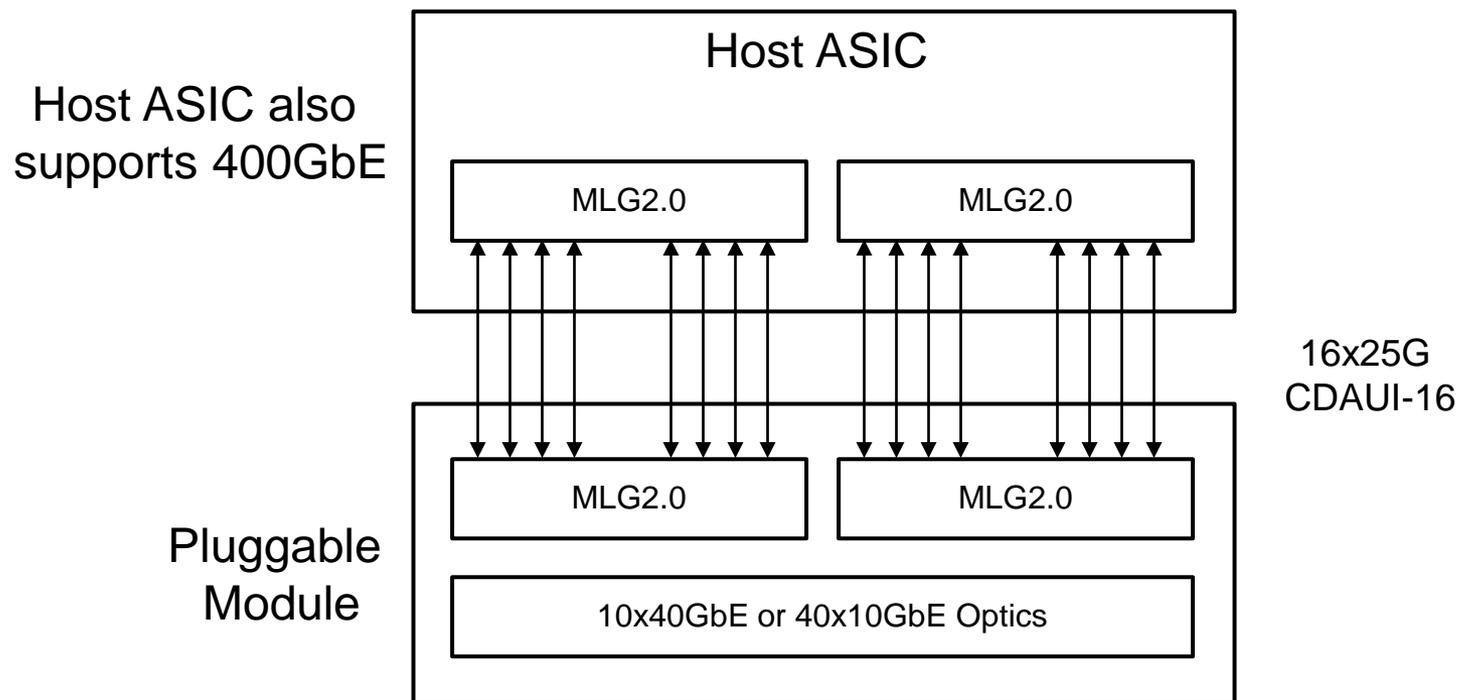


MLG and 400GbE

- The following slides show how MLG 1.0 and 2.0 can be used to carry nx40GbE and nx10GbE across CDAUI interfaces
- So instead of defining 40Gb/s lane modes, can MLG be used?
- MLG is based on 5G VLs, 400GbE can be based on 25G VLs and MLG can be used to carry 40GbE across the same 400GbE electrical interfaces
- Using 25G lanes precludes a CDAUI-10, but likely not needed given the MLG capability?

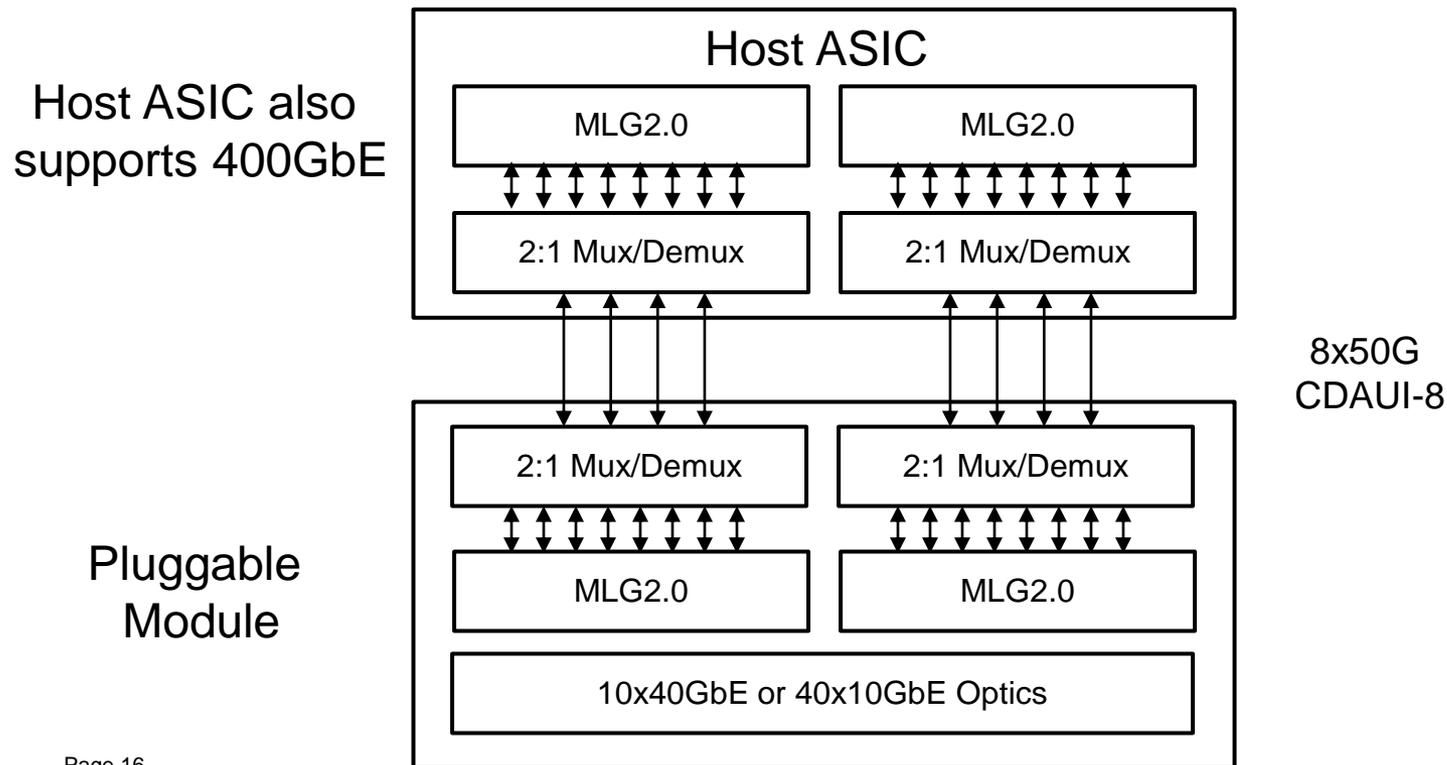
MLG Across CDAUI-16

- How to carry 10x40GbE or 40x10GbE across a 16 lane 400GbE electrical interface?
- Very simple, MLG 2.0 is defined to support 5x40GbE (or 20x10GbE) across 8 lanes of 25G SerDes, so run two instances of MLG 2.0 across the 16x25G interface



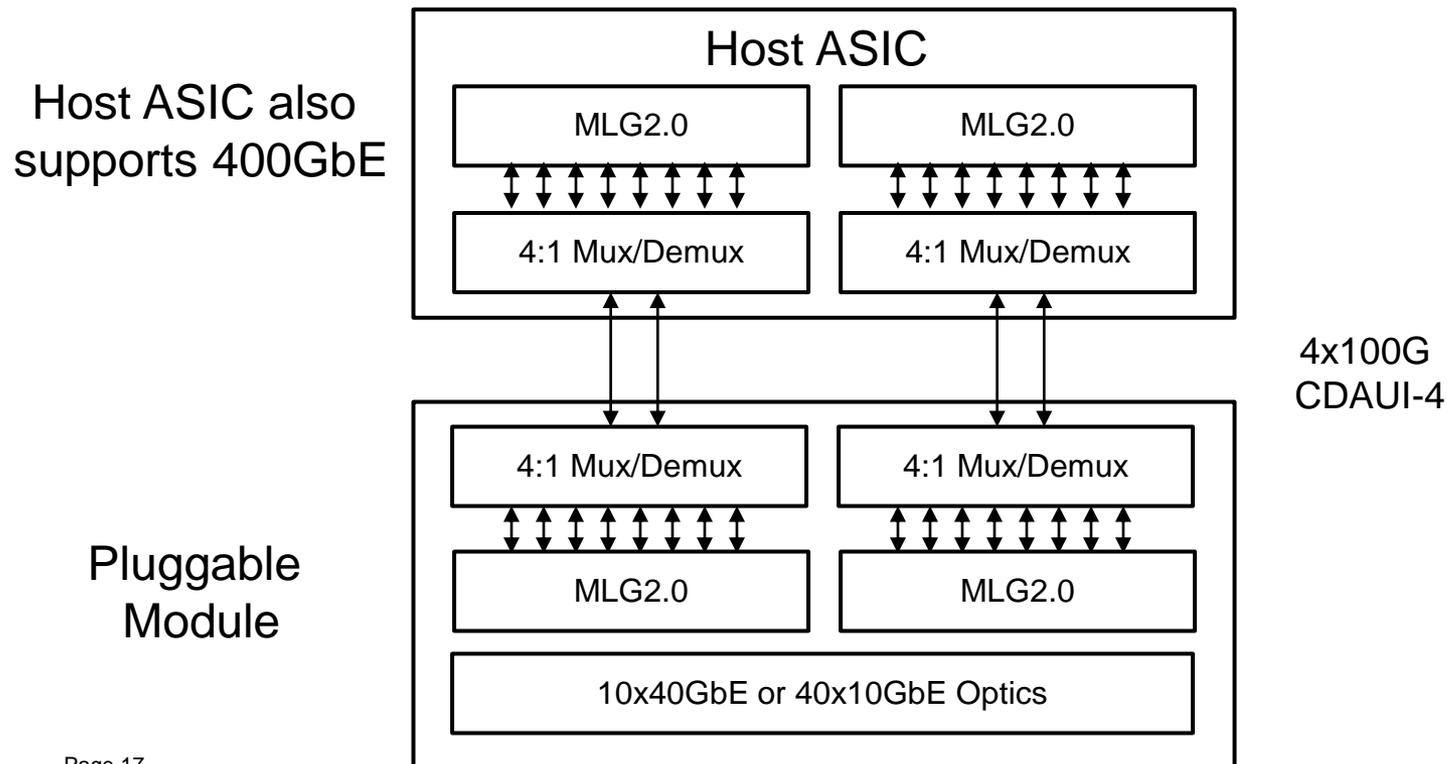
MLG Across CDAUI-8

- How to carry 10x40GbE or 40x10GbE across an 8 lane 400GbE electrical interface?
- Very simple, MLG 2.0 is defined to support 5x40GbE (or 20x10GbE) across 8 lanes of 25G SerDes, so run two instances of MLG 2.0 across the 16x25G interface and then mux one more time to 50G



MLG Across CDAUI-4

- How to carry 10x40G or 40x10GbE across a 4 lane 400GbE electrical interface?
- Very simple, MLG 2.0 is defined to support 5x40GbE (or 20x10GbE) across 8 lanes of 25G SerDes, so run two instances of MLG 2.0 across the 16x25G interface and then mux one more time to 50G



Summary

- Chip-to-module lane widths: 16, 10, 8, 4
- PMD lane widths: 16, 10, 8, 4
- If we do MLD, then the LCM of these is 80!
 - With 10 being the sticky number that causes a jump in number of PCS lanes
 - Question to answer: Is there is likely to be something that works for 400GBASE-R10 but not 400GBASE-R8 that is not a short term technology limit
 - Would the IEEE really standardize two electrical interfaces (CDAUI-8 and CDAUI-10) that are so similar, and can lead to plug and play issues?
- MLG can remain unchanged and stay with 5G VLs and support 10G, 40G etc. across CDAUI-16, -8 etc...
- A lot of questions remain around FEC
- Need to look at tradeoffs of direct 40G support

Interface Type	Lane Widths the Architecture should support over time?					
Chip-to-module I/F	16	10	8	4	2	1
PMD Lanes	16	10	8	4	2	1

Thanks!